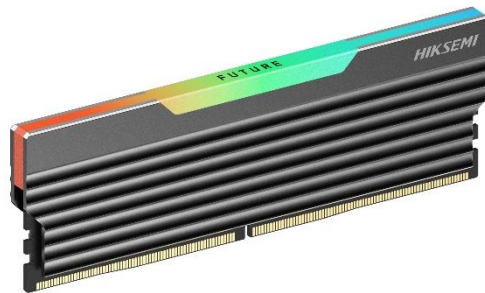


FUTURE UDIMM DDR5

Introduction

HIKSEMI memory module FUTURE UDIMM is a DDR5 memory module, which is made of high-quality DRAM chips and mature production technology, which makes it more compatible, stable and cost-effective. Can be widely used in PC installations, various high-bandwidth, high-performance system applications



Features

- Cost-effective
Adopt selected IC to make the system run stably and perform better.
- Good compatibility
Better compatibility, compatible with more products after HIKSEMI optimization.

Specification

Name	FUTURE UDIMM DDR5
Capacity	16GB/32GB
Interface	DDR5
Frequency	6000/6400/6800/7200/7600/(8000)MHz
Voltage	1.35V/1.4V/1.45V/1.5V
Sequential	CL38/CL36/CL34/CL32/CL30
Overclock model	XMP/EXPO
Pin	288pin
PCB Size(L×W×H mm)	133.25*31.25*3.77
Operation temperature	0 °C to 85 °C (32 °F to 185 °F)
Limited warranty period	Lifetime warranty
Weight	70g

DDR	Interface	Capacity	Frequency	Voltage	Timing	Model	Model Name	Color
UDIMM	DDR5	16G	XMP6000	1.4V	CL36	Future RGB	HSC516U60C4 16G	Black
UDIMM	DDR5	16G	XMP6400	1.35V	CL32	Future RGB	HSC516U64C4 16G	Black
UDIMM	DDR5	16G	XMP6800	1.4V	CL34	Future RGB	HSC516U68C4 16G	Black
UDIMM	DDR5	16G	XMP7200	1.45V	CL34	Future RGB	HSC516U72C4 16G	Black
UDIMM	DDR5	16G	XMP7600	1.45V	CL36	Future RGB	HSC516U76C4 16G	Black
UDIMM	DDR5	16G	XMP8000	1.5V	CL38	Future RGB	HSC516U80C4 16G	Black
UDIMM	DDR5	32G	XMP6000	1.35V	CL30	Future RGB	HSC532U60C4 32G	Black
UDIMM	DDR5	32G	XMP6400	1.35V	CL32	Future RGB	HSC532U64C4 32G	Black

Note

1. Models with frequency of 6000 MHz and above support both Intel XMP 3.0 and AMD E.X.P.O. Other models only support Intel XMP 3.0.
2. Instructions: high-overclocking memory needs to be equipped with a matching motherboard and processor to unleash its overclocking performance. Please verify before the purchase whether your motherboard and CPU support the specifications of DRAM.
3. Please contact the local sales for detailed model information.

Revision History

Version	Description	Date
V1.0.0	FUTURE UDIMM DDR5	20240614

Data subject to change without notice.

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